

malcom

SRS-1C

VDM-3

Reflow Simulator

Video Camera Capture System



**Simulate the temperature profile of your Reflow oven.
Observe the melting state of solder paste.
Easy to simulate of SMT temperature profile.**

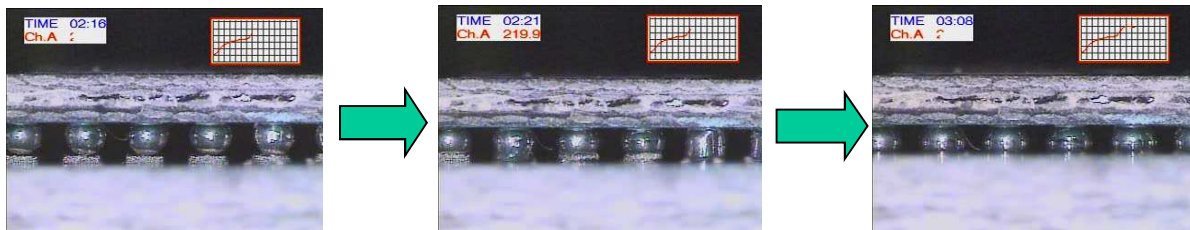
株式会社 マルコム

Special Features

- The hot air and IR blower from the lower-face heaters make it possible to simulate the almost actual conditions of reflow oven.
- The proprietary software analyzes the profile, setting the heating conditions easily.
- Receive the solder paste melting process etc. from SRS-1C compliant with the VDM-3 and simultaneously overlaps onto images taken with the video camera. (Option)
- SFA-1 simulates the temperature profile with hot air, which is the almost actual reflow oven, and evaluates the solderability with the height and width of solder bump of CSP/BGA and the fillet form (Solder height and angle) of Chip part 0402 size. (Option)

Option

Video Camera Capture System VDM-3



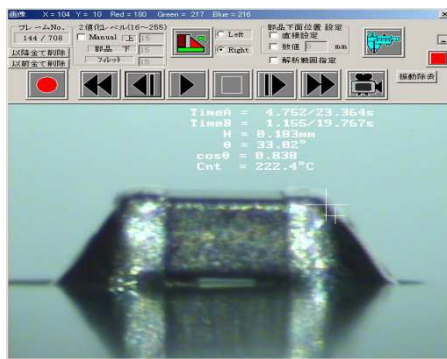
Before Melting

Within Melting

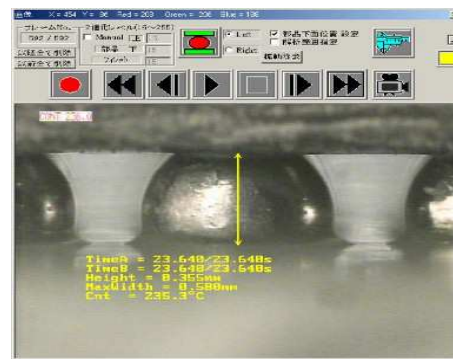
After Melting

BGA bump melting procedure taken with VDM-3

SFA-1



0402 Fillet analysis example



The height and width BGA Solder bump analysis example

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